

What is claimed is:

1. A non-contact ID card or the like, comprising an antenna circuit board where an antenna is formed on a substrate and an interposer board where an enlarged electrode to be connected to an electrode of an IC chip is formed on a substrate mounted with the IC chip, and laminating said antenna circuit board and said interposer board in such a manner that the electrode of the antenna comes in direct contact with the enlarged electrode;

characterized in that the enlarged electrode is a resin electrode made of a conductive resin containing thermoplastic resin.

2. The non-contact ID card or the like of claim 1, further characterized in that a portion of the molecular chain of the thermoplastic resin is modified with a reactive group.

3. The non-contact ID card or the like of claim 1 or 2, further characterized in that the IC chip is embedded in the substrate.

4. A method of manufacturing a non-contact ID card or the like, comprising an antenna circuit board where an antenna is formed on a substrate and an interposer board where an enlarged electrode to be connected to an electrode of an IC chip is formed on a substrate mounted with the IC chip, and joining the electrode of the antenna and the enlarged electrode to come in direct contact with each other by pressurizing and heating, after laminating said antenna circuit board and said interposer board in such a manner that the positions of the antenna electrode and the enlarged electrode are aligned;

characterized in that the enlarged electrode is provided as a resin electrode which is formed through the application of a conductive resin paste containing a thermoplastic resin on the substrate.

5. The method of manufacturing a non-contact ID card or the like of claim 4, further characterized in that a portion of the molecular chain of the thermoplastic resin modified with a reactive group is used as the thermoplastic resin.

6. The method of manufacturing a non-contact ID card or the like of claim 5, further characterized in that the IC chip is embedded in and mounted on the substrate.

7. The method of manufacturing a non-contact ID card or the like of claim 4, 5 or 6, further characterized in that the application of the conductive resin paste is carried out by a screen printing method.